

CMOS 8-Input NOR/OR Gate

High-Voltage Types (20-Volt Rating)

■ CD4078B NOR/OR Gate provides the system designer with direct implementation of the positive-logic 8-input NOR and OR functions and supplements the existing family of CMOS gates.

The CD4078B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

POWER DISSIPATION PER PACKAGE (P_D): For $T_A = -55^{\circ}C$ to $+100^{\circ}C$

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

LEAD TEMPERATURE (DURING SOLDERING):

Features:

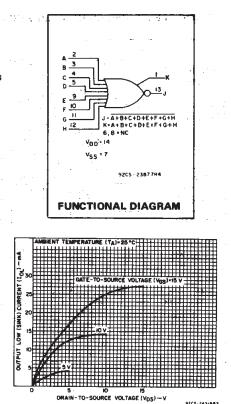
Voltages referenced to V_{SS} Terminal)-0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS-0.5V to V_{DD} +0.5V DC INPUT CURRENT, ANY ONE INPUT±10mA

For T_A = +100°C to +125°C.....Derate Linearity at 12mW/°C to 200mW

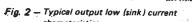
 $\label{eq:FORTA_$

At distance 1/18 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max+265°C

- Medium-Speed Operation: tpHL, tpLH = 75 ns (typ.) at VDD = 10 V
- Buffered inputs and output
- 5-V, 10-V, and 15-V parametric ratings
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μ A at 18 V over full package temperature range: 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):
 1 V at VDD = 5 V
 2 V at VDD = 10 V
 2.5 V at VDD = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



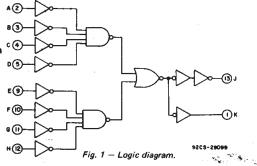
CD4078B Types

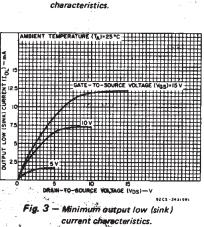


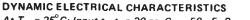
RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	Min.	Max.	Units
Supply-Voltage Range			
(For T _A Full Package Temperature Range)	3	18	v

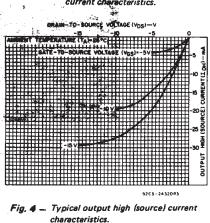






At $T_A = 25^{\circ}C$; Input t_r , $t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}$, $R_L = 200 \text{ k}\Omega$

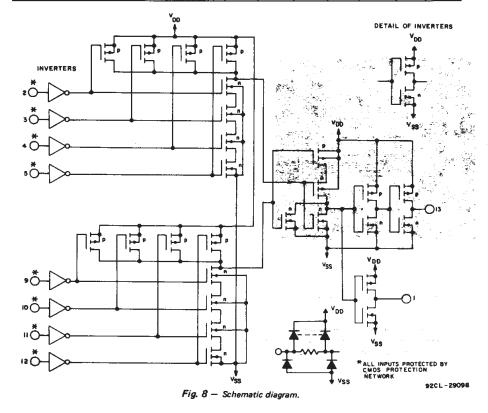
CHARACTERISTIC	TEST CONDI	TIONS	LIN		
		V _{DD} VOLTS	TYP.	MAX.	
Propagation Delay Time,		5	150	300	1
^t PHL, ^t PLH		10	75	150	ns
		15	55	110	
The second state of the second state		5	100	200	1
Transition Time,		10	50	100	ns
^t THL ^{, t} TLH		15	40	80	
Input Capacitance, CIN	Any Input		5	7.5	pF

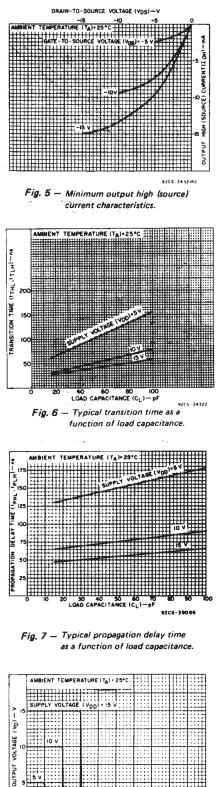


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STATIC ELECTRICAL CHARACTERISTICS

CHARACTER	COND	IS	LIMITS AT INDICATED TEMPERATURES (°C)								
ISTIC	٧o	VIN	VDD					<u> </u>	+25		UNITS
	(V)	(V)	(V)	55	-40	+85	+125	Min.	" Тур,	Max.	
Quiescent Device	-	0,5	5	0.25	0.25	7.5	7.5	-	0.01	0.25	
Current,	-	0,10	10	0.5	0.5	15	15	-	0.01	0.5	
DD Max	-	0,15	15	1	1	30	30	-	0.01	1	μA
2000 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 - 1990 -	-	0,20	20	5	5	150	150	-	0.02	5	
Output Low (Sink) Current IOL Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1		
	0.5	0,10	10	1.6	1.5	11	0.9	13	2.6		
	1.5	0,15	15	4.2	4	2.8	2.4	34	6.8		
Output High (Source) Current, IOH Min.	4.6	0,5	5	-0.64	-0.61	0.42	- 0.36	~0.51	- 1		. mA
	2.5	0,5	5	-2	-18	-1.3	-1 15	-16	-32		
	9,5	0,10	10	-16	-1.5	-11	-0.9	-1.3	-26		
TOH MILLS	13.5	0,15	15	-4.2	- 4	-2.8	-2.4	-3.4	-68		
Output Voltage:	-	0,5	5	0.05					0	0.05	
Low-Level, Vol. Max.	-	0,10	10		0	.05			0	0.05	V
VOL Max.		0,15	15		0	.05			0	0.05	
Output Voltage: *		0,5	5		4	95		4.95	5		
High Level		0,10	10		9	.95		9,95 1	10		
VOH Min.	-	0.15	15		14	1.95		14.95	15		
Input Low	0.5,4.5	<u> </u>	5		1	.5		<u> </u>	-	1.5	
Voltage,	1,9	_	10			3		-	—	3	~
VIL Max.	1.5,13.5	Í	. 15			4		-	-	4	
Input High Voltage, VIH Min.	0.5,4.5		5		3	3.5		3.5	-		
	1,9	-	10			7		1	-	-	
	1.5,13.5	_	15		1	1		11	-	-	
Input Current	1997 - A	0,18	18	± 0.1	± 0.1	±1	±1	-	±10 ⁻⁵	±0.1	μA





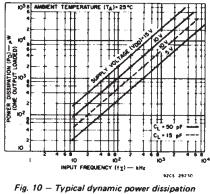
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INPUT VOLTAGE (VI) - V

Fig. 9. - Typical voltage transfer charac-

teristics (NOR output).



as a function of frequency.

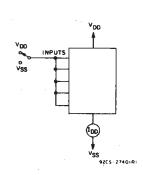


Fig. 11 - Quiescent-device-current test circuit.

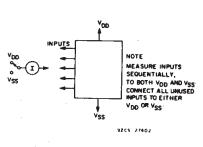
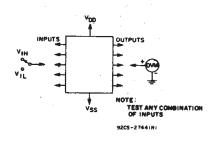


Fig. 12 - Input current test circuit.



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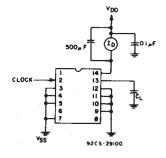
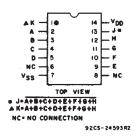
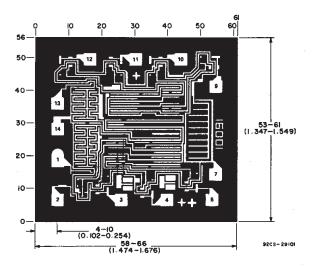


Fig. 14 - Dynamic power dissipation test circuit.

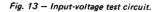


TERMINAL ASSIGNMENT



Dimensions and pad layout for CD4078BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
7704402CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704402CA CD4078BF3A	Samples
CD4078BE	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4078BE	Samples
CD4078BF	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4078BF	Samples
CD4078BF3A	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704402CA CD4078BF3A	Samples
CD4078BM	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	CD4078BM	
CD4078BM96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4078BM	Samples
CD4078BMT	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-55 to 125	CD4078BM	
CD4078BNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4078B	Samples
CD4078BPW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-55 to 125	CM078B	
CD4078BPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM078B	Samples
CD4078BPWRE4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM078B	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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PACKAGE OPTION ADDENDUM

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4078B, CD4078B-MIL :

- Catalog : CD4078B
- Military : CD4078B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

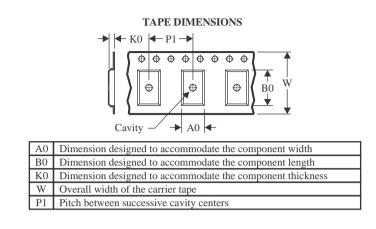


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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



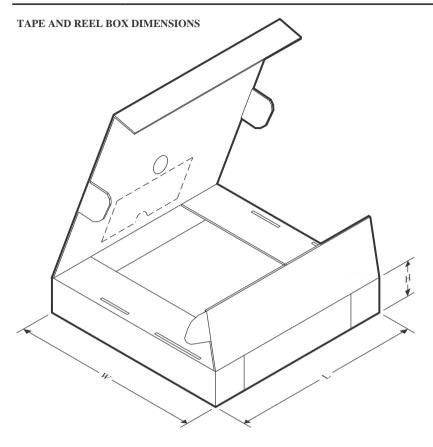
*All dimensions are nomina	al											
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4078BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4078BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4078BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

12-May-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4078BM96	SOIC	D	14	2500	356.0	356.0	35.0
CD4078BNSR	SO	NS	14	2000	356.0	356.0	35.0
CD4078BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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12-May-2023

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD4078BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4078BE	N	PDIP	14	25	506	13.97	11230	4.32

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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